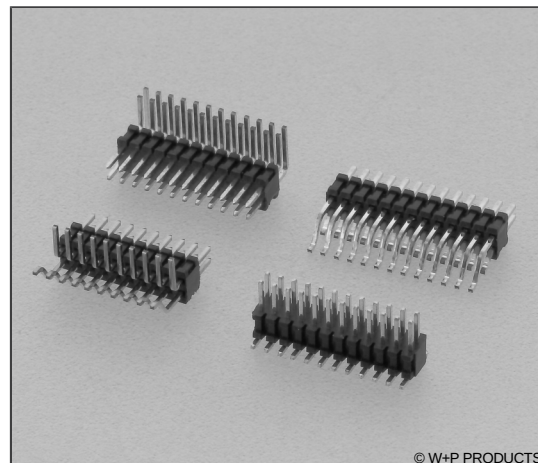


SMT-/ Mixed Technology Stiftleisten RM 1,27mm, 2-reihig

SMT/Mixed Technology Pin Headers, 1.27mm Pitch, Double Row

Technische Daten / Technical Data

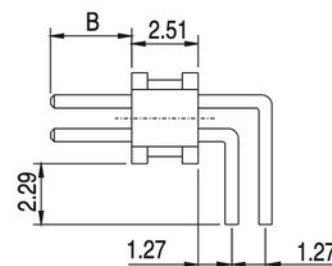
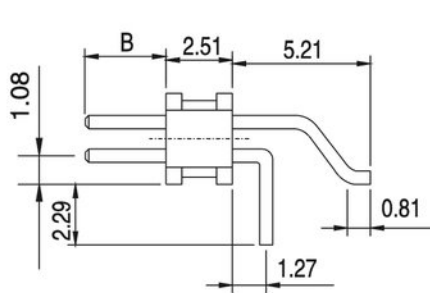
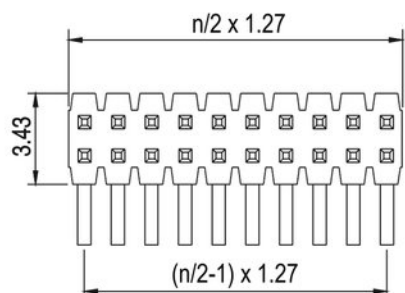
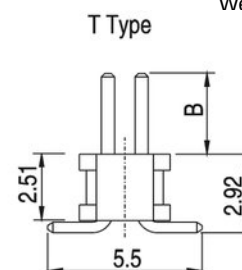
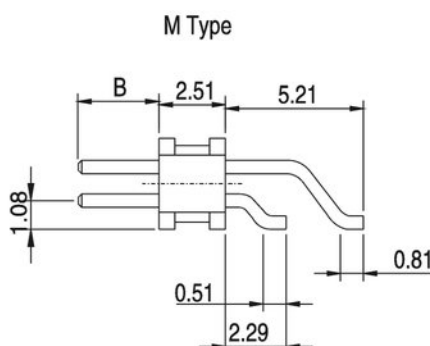
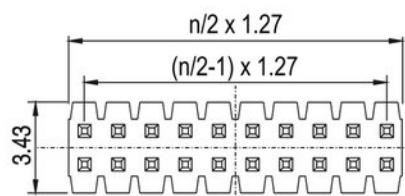
Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Vierkantstift 0,40mm, Kupferlegierung
Contact Material	0.40mm square pin, copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	Acc. to options (see below), over Ni (1.3 ... 2.5µm)
Durchgangswiderstand	< 20mΩ
Contact Resistance	< 20mΩ
Isolationswiderstand	> 500MΩ
Insulation Resistance	> 500MΩ
Spannungsfestigkeit	500V _{AC}
Test Voltage	500V _{AC}
Nennspannung	250V _{AC}
Voltage Rating	250V _{AC}
Nennstrom	1A
Current Rating	1A
Temperaturbereich	-40°C ... +105°C
Temperature Range	-40°C ... +105°C
Verarbeitung	Reflow- oder Wellen-Lötverfahren
Processing	Reflow- or wave soldering



© W+P PRODUCTS

Passende Buchsenleisten:
Compatible Female Headers:
713 7130 etc.

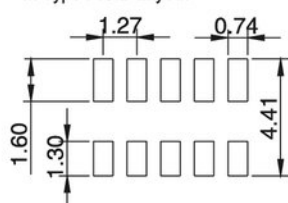
Weitere siehe Kapitel B
more



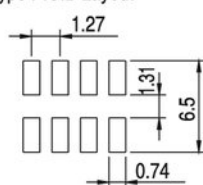
D Type

R Type

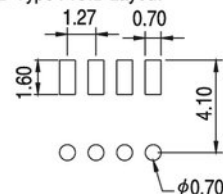
M Type P.C.B Layout



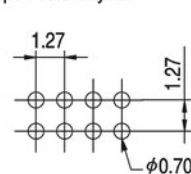
T Type P.C.B Layout



D Type P.C.B Layout



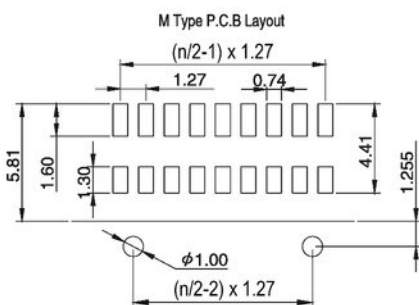
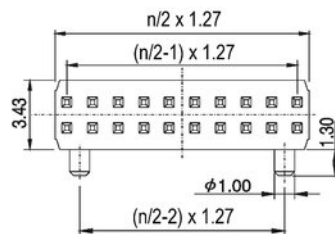
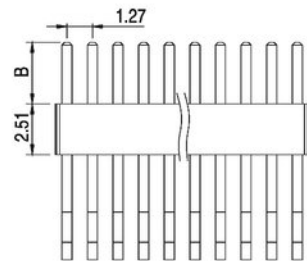
R Type P.C.B Layout



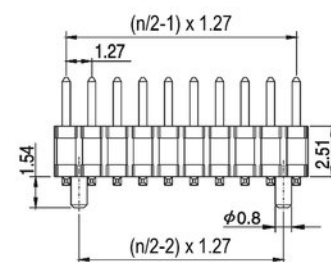
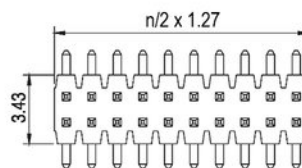
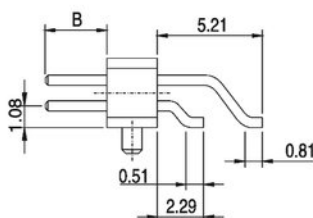
Series	Type*	Dimensions*	Contacts*	Plating*	Loc. Pegs	Packaging*
7076	1	10	004	50	00	PPST
	1 D-Type 2 M-Type 3 T-Type 4 R-Type	10 B=3,05mm 20 B=1,91mm 30 B=1,65mm 40 B=3,81mm	004-100 Zweireihig Double row	00 Vergoldet Gold plated 50 Verzinnt Tin plated 60 Sel. Au/Sn Duplex plating	00 Ohne Pos.hilfen W/o loc. pegs	ST PPST PPTR (Option)

7076

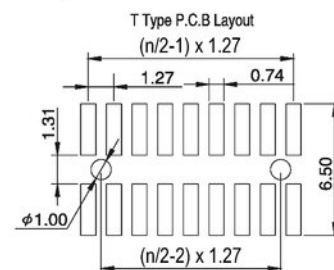
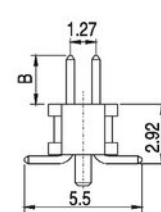
SMT-/ Mixed Technology Stifleleisten RM 1,27mm, 2-reihig
SMT/Mixed Technology Pin Headers, 1.27mm Pitch, Double Row



M Type



T Type



Series	Type*	Dimensions*	Contacts*	Plating*	Loc. Pegs	Packing*
7076	2	10	004	50	10	PPST
	2 M-Type 3 T-Type	10 B=3,05mm 20 B=1,91mm 30 B=1,65mm 40 B=3,81mm	004-100 Zweireihig Double row	00 Vergoldet Gold plated 50 Verzinnt Tin plated 60 Sel. Au/Sn Duplex plating	10 Mit Pos.hilfen With loc. pegs	ST In Stangen ohne Pick&Place-Pads In tubes w/o Pick&Place-Pads PPST In Stangen mit P&P-Pads In tubes with P&P-Pads PPTR (Option) Tape & Reel mit P&P-Pads Tape & Reel with P&P-Pads

* Dies ist ein **Bestellbeispiel** -
 bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** -
 please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads
PPTR (Option) Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

